2SA836

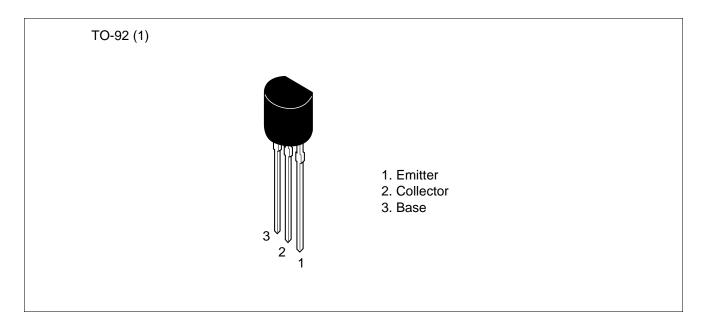
Silicon PNP Epitaxial

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Application

Low frequency low noise amplifier

Outline



2SA836

Absolute Maximum Ratings (Ta = 25°C)

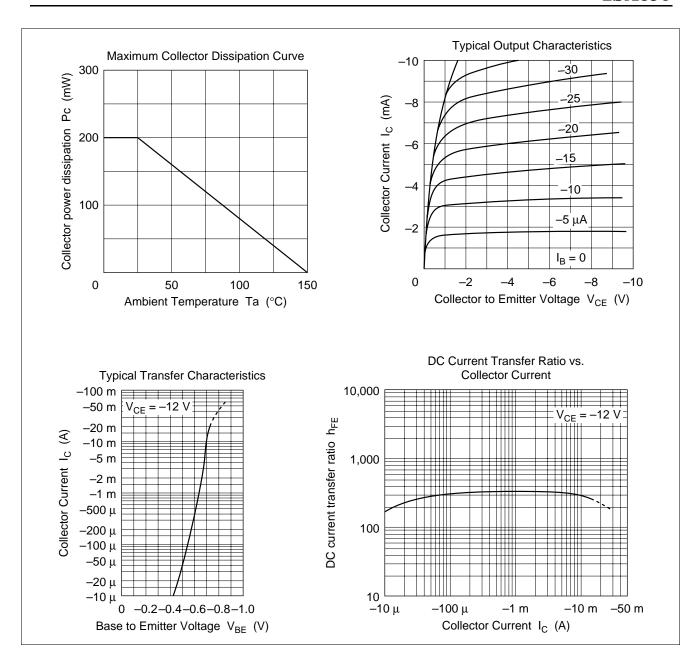
Item	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	-55	V
Collector to emitter voltage	V_{CEO}	-55	V
Emitter to base voltage	V_{EBO}	-5	V
Collector current	I _c	-100	mA
Emitter current	I _E	100	mA
Collector power dissipation	P _c	200	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

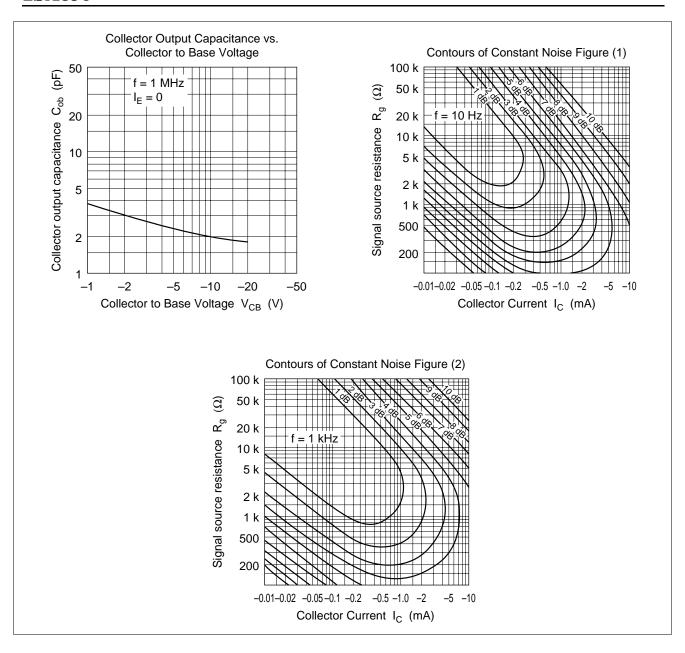
Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	- 55	_	_	V	$I_{c} = -10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	- 55	_	_	V	$I_{c} = -1 \text{ mA}, R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	- 5	_	_	V	$I_{E} = -10 \ \mu A, \ I_{C} = 0$
Collector cutoff current	I _{CBO}	_	_	-100	nA	$V_{CB} = -18 \text{ V}, I_{E} = 0$
Emitter cutoff current	I _{EBO}	_	_	- 50	nA	$V_{EB} = -2 \text{ V}, I_{C} = 0$
DC current transfer ratio	h _{FE} *1	160	_	500		$V_{CE} = -12 \text{ V}, I_{C} = -2 \text{ mA}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	-0.1	-0.5	V	$I_{\rm C} = -10 \text{ mA}, I_{\rm B} = -1 \text{ mA}$
Base to emitter voltage	V_{BE}	_	-0.66	-0.75	V	$V_{CE} = -12 \text{ V}, I_{C} = -2 \text{ mA}$
Gain bandwidth product	f _T	_	200	_	MHz	$V_{CE} = -12 \text{ V}, I_{E} = -2 \text{ mA}$
Collector output capacitance	Cob	_	2.0	_	pF	$V_{CB} = -10 \text{ V}, I_{E} = 0, f = 1\text{MHz}$
Noise figuer	NF	_	1	5	dB	$V_{CE} = -6 \text{ V}, \qquad f = 10 \text{ Hz}$
		_	0.5	1	dB	$ \begin{array}{ll} \hline \\ I_{\text{C}} = -0.1 \text{mA}, & \hline \\ R_{\text{g}} = 10 \text{ k} \Omega \end{array} $ f = 1 kHz

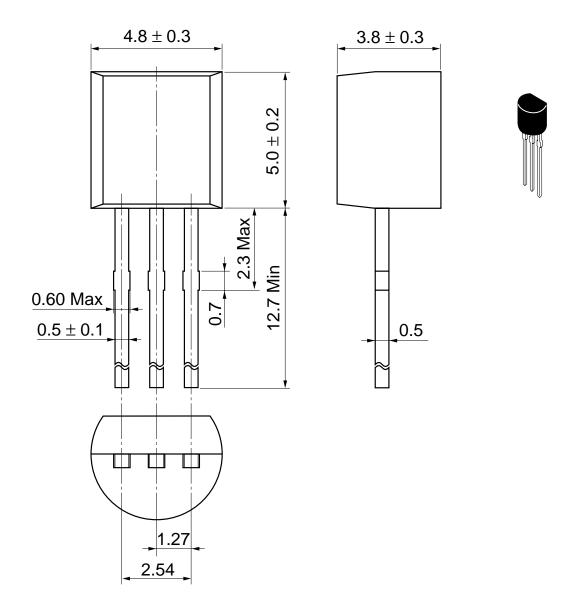
Note: 1. The 2SA836 is grouped by h_{FE} as follows.

С	D
160 to 320	250 to 500





Unit: mm



Hitachi Code	TO-92 (1)
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.25 g

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Hitachi, Ltd.

Semiconductor & Integrated Circuits.

Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

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For further information write to:

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive, San Jose,CA 95134 Tel: <1> (408) 433-1990 Fax: <1>(408) 433-0223 Hitachi Europe GmbH Electronic components Group Dornacher Stra§e 3 D-85622 Feldkirchen, Munich Germany

Tel: <49> (89) 9 9180-0 Fax: <49> (89) 9 29 30 00

Hitachi Europe Ltd. Electronic Components Group Whitebrook Park Lower Cookham Road Maidenhead

Berkshire SL6 8YA, United Kingdom Tel: <44> (1628) 585000 Fax: <44> (1628) 778322

Hitachi Asia Pte. Ltd. 16 Collyer Quay #20-00 Hitachi Tower Singapore 049318 Tel: 535-2100 Fax: 535-1533

Hitachi Asia Ltd. Taipei Branch Office

3F, Hung Kuo Building. No.167, Tun-Hwa North Road, Taipei (105) Tel: <886> (2) 2718-3666 Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road, Tsim Sha Tsui, Kowloon, Hong Kong Tel: <852> (2) 735 9218 Fax: <852> (2) 730 0281

Telex: 40815 HITEC HX

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